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VT-802

Description

Vectron's VT-802 Temperature Compensated Crystal Oscillator (TCXO) is a quartz stabilized, CMOS output, analog temperature compensated oscillator, operating off either 2.5 or 3.3 volt supply in a hermetically sealed 5.0x3.2 ceramic package.

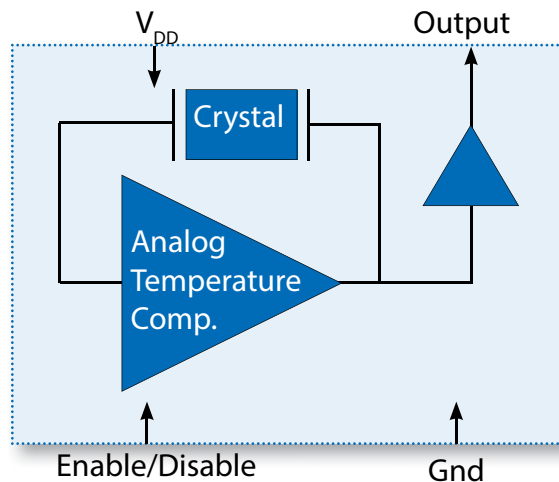
Features

- CMOS Output
- Low Power
- Output Frequencies to 50 MHz
- Low Jitter Fundamental Crystal Design
- Hermetically Sealed Ceramic SMD package
- Product is compliant to RoHS directive  and fully compatible with lead free assembly

Applications

- WiMAX, Wi-Fi, Wi-LAN
- Wireless Communications
- Base Stations
- Point to point radios
- Broadband Access

Block Diagram



Specifications

Table 1. Electrical Performance

Parameter	Symbol	Min.	Typ	Max	Units
Output Frequency	f_o	2		50	MHz
Supply Voltage ¹ , (Ordering Option)	V_{DD}	+2.5 or +3.3			V
Supply Current, 5 to 19.999MHz 20.000 to 50.0000MHz	I_{DD}			3 5	mA mA
Operating Temperature, (Ordering Option)	T_{OP}	-20/70 or -40/85			°C
STABILITY					
Stability Over T_{OP} , (Ordering Option)		±2.0, ±2.5, ±5.0 or ±10			ppm
Initial Accuracy				±1.0	ppm
Power Supply Stability				±0.5	ppm
Load Stability				±0.2	ppm
Aging				±1.0	ppm/yr
OUTPUT					
Output Logic High ² Output Logic Low	V_{OH} V_{OL}	0.9* V_{DD}		0.1* V_{DD}	V
Output Load				15	pF
Output Rise and Fall Time	t_R/t_F			6	ns
Duty Cycle		45		55	%
Phase Noise, 12.800MHz 10Hz 100Hz 1kHz 10kHz 100kHz	θ_N		-70 -108 -138 -155 -159		dBc/Hz
Start Up Time	t_{SU}			2	ms
Enable Disable Function					
Input Logic High ³ Input Logic Low	V_{IH} V_{IL}	0.3* V_{DD}		0.7* V_{DD}	V V
Package		5x3.2.1.1			mm

1. The VT-802 power supply pin should be filtered, eg, a 0.1 and 0.01uf capacitor.
2. The Output is DC coupled.
3. The Output is active if the Enable Disable is left open.

Outline Drawing and Recommended Layout

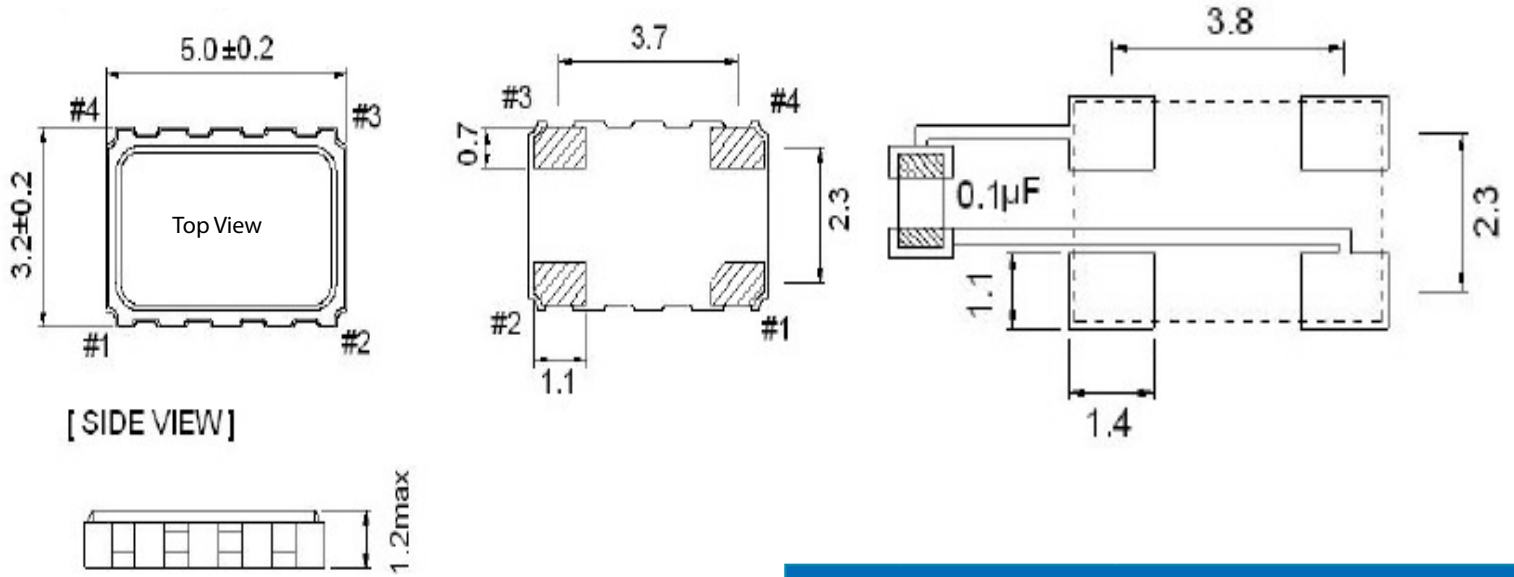


Table 2. Pinout

Pin #	Symbol	Function
1	E/D	Enable/Disable Function
2	GND	Electrical and Lid Ground
3	f_o	Output Frequency
4	V_{DD}	Supply Voltage

Maximum Ratings

Absolute Maximum Ratings and Handling Precautions

Stresses in excess of the absolute maximum ratings can permanently damage the device. Functional operation is not implied or any other excess of conditions represented in the operational sections of this data sheet. Exposure to absolute maximum ratings for extended periods may adversely affect device reliability.

Although ESD protection circuitry has been designed into the VT-802, proper precautions should be taken when handling and mounting, VI employs a Human Body Model and Charged Device Model for ESD susceptibility testing and design evaluation.

ESD thresholds are dependent on the circuit parameters used to define the model. Although no industry standard has been adopted for the CDM a standard resistance of 1.5kOhms and capacitance of 100pF is widely used and therefore can be used for comparison purposes.

Table 3. Maximum Ratings

Parameter	Symbol	Rating	Unit
Storage Temperature	T_{STORE}	-55/125	°C
E/D Voltage	E/D	0/ V_{DD}	V
ESD, Human Body Model		1000	V
ESD, Charged Device Model		1000	V

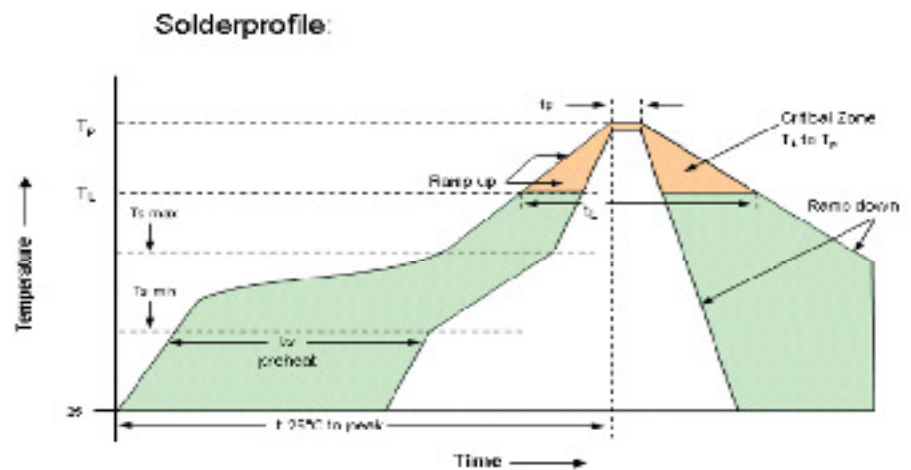
Table 4. Environmental Compliance	
Parameter	Condition
Mechanical Shock	MIL-STD-883 Method 2002
Mechanical Vibration	MIL-STD-883 Method 2007
Temperature Cycle	MIL-STD-883 Method 1010
Solderability	MIL-STD-883 Method 2003
Fine and Gross Leak	MIL-STD-883 Method 1014
Resistance to Solvents	MIL-STD-883 Method 2015
Moisture Sensitivity Level	MSL1
Contact Pads	Gold over Nickel

IR Reflow

Suggested IR Profile

Devices are built using lead free epoxy and can be subjected to standard lead free IR reflow conditions shown in Table 5. Contact pads are gold over nickel and lower maximum temperatures can also be used, such as 220C.

Table 5. Reflow Profile		
Parameter	Symbol	Value
PreHeat Time	t_s	200 sec Max
Ts-min		150°C
Ts-max		200°C
Ramp Up	R_{UP}	3°C/sec Max
Time above 217C	t_L	150 sec Max
Time to Peak Temperature	$t_{25C \text{ to peak}}$	480 sec Max
Time at 260C	t_p	30 sec Max
Time at 240C	t_{p2}	60 sec Max
Ramp down	R_{DN}	6°C/sec Max



Tape & Reel

Table 6. Tape and Reel Information

Tape Dimensions (mm)					Reel Dimensions (mm)							#/Reel
W	F	Do	Po	P1	A	B	C	D	N	W1	W2	
18	1.75	1.55	4	4	178	2.5	13	22	60	11.5	15	1000

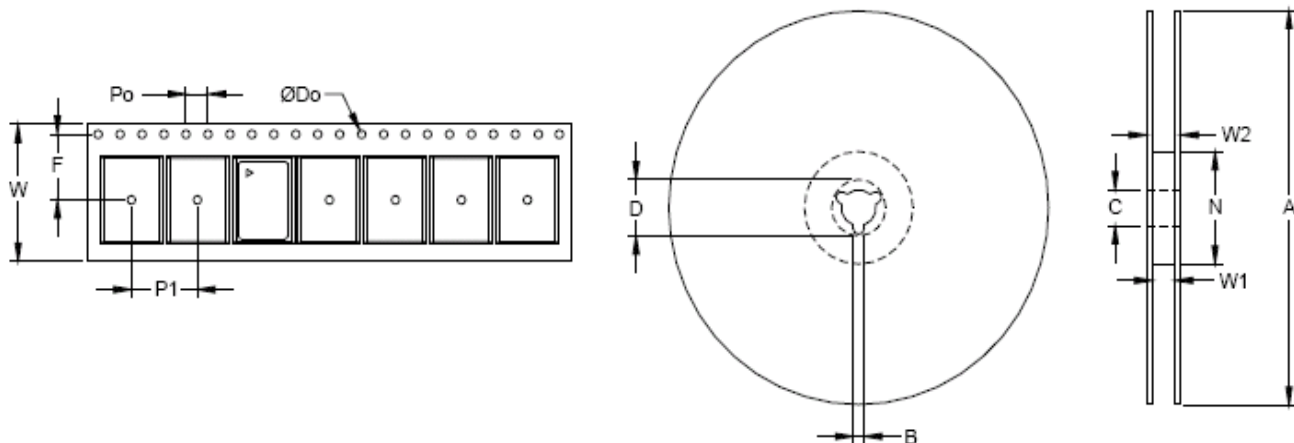
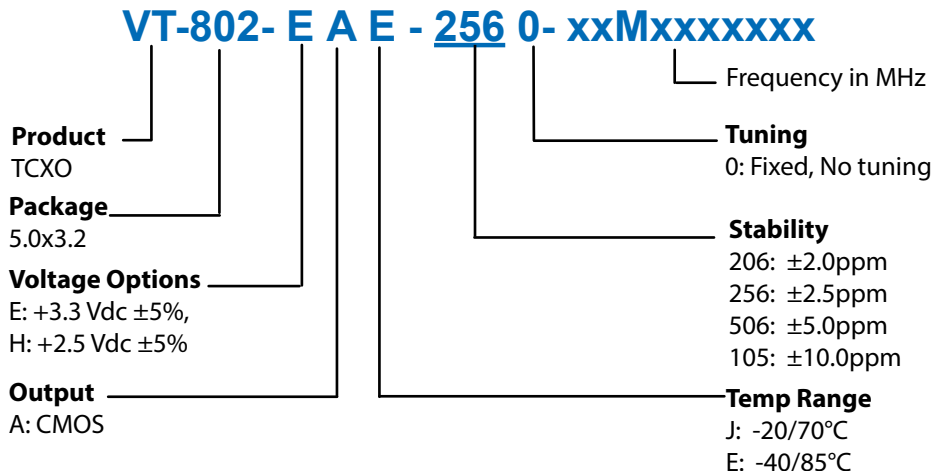


Table 7. Standard Frequencies (MHz)

2.04815328	10.000	12.800	14.7456	16.384	19.200	19.440	20.000	25.000	26.000
27.000	32.000	40.000	50.000						

Ordering Information



**Note: not all combination of options are available.
Other specifications may be available upon request.*

Example: VT-802-EAE-2560-19M2000000

* Add **_SNPBDIP** for tin lead solder dip
Example: VT-802-EAE-2560-19M2000000_**_SNPBDIP**

Revision History

Revision Date	Approved	Description
Aug 10, 2018	FB	Update logo and contact information, add "SNPBDIP" ordering option



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